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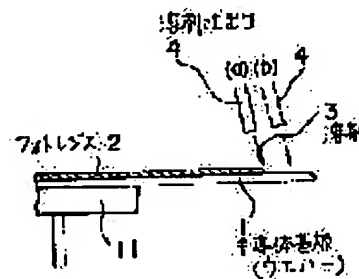
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(54) MANUFACTURE FOR SEMICONDUCTOR DEVICE AND SUBSTRATE CLEANER USED THEREFOR

(57)Abstract:

PURPOSE: To provide a method for fabricating a semiconductor device for removing resist around a semiconductor substrate including residual thereby suppressing contamination by the resist around the substrate and dust generation and to provide a substrate cleaner usable in the method.

CONSTITUTION: A method for fabricating a semiconductor device including steps for forming photoresist 2 on a semiconductor substrate 1 and cleaning to remove the photoresist 2 around the substrate 1 comprises at least a first cleaning process with photoresist solvent and a second cleaning process for removing residual of the first cleaning process. The second cleaning is done for example at a farther position (position (b)) from the substrate than the first cleaning (position (a)) or under conditions of lower resist solubility of the resist than that for the first cleaning to provide the fabricating method and a substrate cleaner used for the method.



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